

INTERNATIONAL STANDARD



BASIC EMC PUBLICATION

**Electromagnetic compatibility (EMC) –
Part 4-36: Testing and measurement techniques – IEMI immunity test methods
for equipment and systems**



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CONTENTS

| | |
|---|----|
| FOREWORD | 7 |
| INTRODUCTION | 9 |
| 1 Scope | 10 |
| 2 Normative references | 10 |
| 3 Terms, definitions and abbreviated terms | 10 |
| 3.1 Terms and definitions | 10 |
| 3.2 Abbreviated terms | 14 |
| 4 General | 15 |
| 5 IEMI environments and interaction | 16 |
| 5.1 General | 16 |
| 5.2 IEMI environments | 17 |
| 5.2.1 Technical capability groups | 17 |
| 5.2.2 IEMI deployment scenarios | 17 |
| 5.2.3 Radiated IEMI environment summary | 17 |
| 5.2.4 Published conducted IEMI environments | 18 |
| 5.3 Interaction with victim equipment, systems and installations | 18 |
| 5.3.1 General | 18 |
| 5.3.2 Protection level | 19 |
| 6 Test methods | 20 |
| 6.1 Derivation of applicable test methods | 20 |
| 6.2 Derivation of transfer functions | 21 |
| 6.3 Radiated tests using IEMI simulator | 22 |
| 6.4 Radiated tests using a reverberation chamber | 22 |
| 6.5 Complex waveform injection (CWI) | 22 |
| 6.6 Damped sinusoidal injection (DSI) | 22 |
| 6.7 Electrostatic discharge (ESD) | 22 |
| 6.8 Electrically fast transient (EFT) | 22 |
| 6.9 Antenna port injection | 23 |
| 7 Test parameters | 23 |
| 7.1 Derivation of immunity test parameters | 23 |
| 7.2 Radiated test parameters | 23 |
| 7.2.1 Generic hyperband test parameters (skilled capability group) | 23 |
| 7.2.2 Generic mesoband test parameters (skilled capability group) | 25 |
| 7.2.3 Generic hypoband test parameters (skilled capability group) | 27 |
| 7.3 Generic conducted IEMI test parameters | 28 |
| 7.3.1 General | 28 |
| 7.3.2 Characteristics and performance of the fast damped oscillatory wave generator | 29 |
| 7.4 Tailored test level derivation | 30 |
| 7.5 Relevance of EMC immunity data | 30 |
| Annex A (informative) Failure mechanisms and performance criteria | 31 |
| A.1 General | 31 |
| A.2 Failure mechanisms | 31 |
| A.2.1 General | 31 |
| A.2.2 Noise | 32 |

| | | |
|-----------------------|--|----|
| A.2.3 | Parameter offset and drifts | 32 |
| A.2.4 | System upset or breakdown..... | 33 |
| A.2.5 | Component destruction..... | 33 |
| A.3 | Effect of pulse width..... | 34 |
| A.4 | Performance criteria | 34 |
| A.5 | References | 35 |
| Annex B (informative) | Developments in IEMI source environments | 37 |
| B.1 | General..... | 37 |
| B.2 | IEMI environment..... | 38 |
| B.3 | IEMI sources..... | 39 |
| B.4 | Published radiated IEMI environments | 43 |
| B.4.1 | IEC 61000-2-13 [B.14] | 43 |
| B.4.2 | Mil-Std-464C | 43 |
| B.4.3 | Selection of parameters for mesoband immunity test | 45 |
| B.4.4 | International Telecommunication Union (ITU) | 47 |
| B.5 | Summary | 47 |
| B.6 | References | 48 |
| Annex C (informative) | Interaction with buildings..... | 50 |
| C.1 | Building attenuation | 50 |
| C.2 | Coupling to cables | 51 |
| C.3 | Low voltage cable attenuation..... | 52 |
| C.4 | References | 53 |
| Annex D (informative) | Relation between plane wave immunity testing and immunity testing in a reverberation chamber | 55 |
| D.1 | General..... | 55 |
| D.2 | Relation between measurements of shielding effectiveness in the two environments | 56 |
| D.3 | Relation between immunity testing in the two environments | 59 |
| D.4 | Additional aspects..... | 61 |
| D.5 | References | 61 |
| Annex E (informative) | Complex waveform injection – Test method..... | 64 |
| E.1 | General..... | 64 |
| E.2 | Prediction | 64 |
| E.2.1 | General | 64 |
| E.2.2 | Example | 68 |
| E.3 | Construction | 70 |
| E.4 | Injection..... | 74 |
| E.5 | Summary | 76 |
| E.6 | References | 76 |
| Annex F (informative) | Significance of test methodology margins | 78 |
| F.1 | General..... | 78 |
| F.2 | Examples..... | 78 |
| F.2.1 | General | 78 |
| F.2.2 | Negative contributions | 79 |
| F.2.3 | Positive contributions..... | 81 |
| F.2.4 | Summary | 83 |
| F.3 | References | 83 |
| Annex G (informative) | Intentional EMI – The issue of jammers | 84 |
| G.1 | General..... | 84 |

| | | |
|--|---|-----|
| G.2 | Effects | 84 |
| G.3 | Published accounts of jamming | 85 |
| G.4 | Risk assessment..... | 85 |
| G.5 | Mitigation | 85 |
| G.6 | References | 86 |
| Annex H (normative) Hyperband and mesoband radiated transients immunity test method | | 88 |
| H.1 | Overview..... | 88 |
| H.2 | Test equipment | 88 |
| H.2.1 | General | 88 |
| H.2.2 | Test facility | 88 |
| H.2.3 | Hyperband transient pulse radiating test system | 89 |
| H.2.4 | Mesoband transient pulse radiating test system..... | 89 |
| H.2.5 | Measurement chain | 89 |
| H.3 | Field uniformity assessment..... | 90 |
| H.3.1 | Field uniformity assessment in an anechoic chamber..... | 90 |
| H.3.2 | Field uniformity in GTEM waveguide..... | 93 |
| H.4 | Test set-up | 93 |
| H.4.1 | General | 93 |
| H.4.2 | Arrangement of table-top equipment | 95 |
| H.4.3 | Arrangement of floor-standing equipment | 95 |
| H.4.4 | Arrangement of wiring..... | 95 |
| H.5 | Test procedure..... | 96 |
| H.5.1 | General | 96 |
| H.5.2 | Laboratory reference conditions..... | 96 |
| H.5.3 | Execution of the test | 96 |
| H.5.4 | Evaluation of test results | 98 |
| H.6 | Test report | 98 |
| H.7 | References | 99 |
| Annex I (informative) Calibration method and measurement uncertainty of sensors for the measurement of radiated hyperband and mesoband transient fields..... | | 100 |
| I.1 | General..... | 100 |
| I.2 | Calibration method in TEM waveguides in IEC 61000-4-20:2010, Annex E [I.1]... | 100 |
| I.2.1 | General | 100 |
| I.2.2 | Probe calibration requirements | 101 |
| I.2.3 | Field probe calibration procedure in case of a one-port TEM waveguide | 102 |
| I.3 | Calibration procedures for D-dot sensors in the time domain..... | 103 |
| I.3.1 | General | 103 |
| I.4 | Measurement uncertainty | 105 |
| I.5 | References | 106 |
| Bibliography..... | | 107 |
| Figure 1 – Example of radiated and conducted IEMI interaction with a building..... | | 19 |
| Figure 2 – Assessment options | | 21 |
| Figure 3 – Examples of ports | | 23 |
| Figure 4 – Example of hyperband waveform..... | | 25 |
| Figure 5 – Example of mesoband waveform..... | | 27 |
| Figure 6 – Typical hypoband/narrowband waveform..... | | 28 |

| | |
|--|----|
| Figure 7 – Waveform of the damped oscillatory wave (open circuit voltage) | 29 |
| Figure A.1 – IEMI induced offset of sensor output – Corruption of information | 32 |
| Figure A.2 – Collision of an induced disturbance with data bits [A.1] | 33 |
| Figure A.3 – Examples of destruction on a chip [A.2] | 33 |
| Figure A.4 – Generic failure trend as a function of pulse width | 34 |
| Figure B.1 – A comparison of HPEM and IEMI spectra [B.6] | 37 |
| Figure B.2 – Representation of typical IEMI radiation and coupling onto systems [B.3] | 39 |
| Figure B.3 – Parameter space in power/frequency occupied by sophisticated IEMI (i.e. DEW) sources in comparison to common RF systems [B.1] | 40 |
| Figure B.4 – Peak power and energy from continuous and pulsed (durations shown) microwave sources, narrowband and wideband | 40 |
| Figure B.5 – Peak powers of various types of pulsed hypoband/narrowband sources [B.1] ... | 41 |
| Figure B.6 – Peak versus average power for microwave sources with duty factors indicated | 41 |
| Figure B.7 – Phase coherence leading to a compact HPM source with N^2 scaling of output power | 42 |
| Figure B.8 – Briefcase mesoband DS source sold by Diehl-Rheinmetall [B.3] | 42 |
| Figure B.9 – A do-it-yourself electromagnetic weapon made from an oven magnetron [B.13] | 43 |
| Figure B.10 – Wideband (mesoband and hyperband) EME derived from [B.17] | 45 |
| Figure B.11 – Plot of entire narrowband system weight as a function of output microwave power for land-mobile and land-transportable systems | 48 |
| Figure C.1 – Typical unprotected low-rise building plane wave E-field attenuation collected from references | 50 |
| Figure C.2 – Cable coupling and resonance region | 52 |
| Figure C.3 – Mains cable attenuation profile | 53 |
| Figure E.1 – LLSC reference field measurement set-up | 65 |
| Figure E.2 – LLSC induced current measurement set-up | 66 |
| Figure E.3 – Typical LLSC magnitude-only transfer function | 66 |
| Figure E.4 – Prediction of induced current using minimum phase constraints | 67 |
| Figure E.5 – IEC 61000-2-9 early-time (E1) HEMP environment | 68 |
| Figure E.6 – Overlay of transfer function and threat (frequency domain) | 69 |
| Figure E.7 – Predicted current | 69 |
| Figure E.8 – Example of de-convolution result | 71 |
| Figure E.9 – Damped sinusoidal waveforms – Ten-component fit | 71 |
| Figure E.10 – Approximated and predicted transient | 72 |
| Figure E.11 – Approximated and predicted transient (0 ns to 100 ns) | 72 |
| Figure E.12 – Approximation and prediction transient – Frequency domain comparison | 73 |
| Figure E.13 – Variation in error for an increasing number of damped sinusoids | 74 |
| Figure E.14 – Complex injection set-up | 75 |
| Figure E.15 – Amplifier requirements for various current levels | 75 |
| Figure E.16 – Comparison of predicted (green) and injected (red) current | 76 |
| Figure F.1 – Variation in induced currents as a result of configuration | 79 |
| Figure F.2 – Comparison of HPD and VPD induced currents | 80 |
| Figure F.3 – System variability | 80 |

Figure F.4 – Comparison of single- and multi-port injection 81

Figure F.5 – Example of transfer functions and worst-case envelope 82

Figure F.6 – Comparison of individual and worst-case transfer function predictions 82

Figure F.7 – Comparison between predicted and measured induced currents 83

Figure H.1 – Measurement chain for field uniformity assessment and transient responses 89

Figure H.2 – Test set-up for field uniformity assessment in anechoic chamber 91

Figure H.3 – Example of test set-up for table-top equipment/system 94

Figure H.4 – Example of test set-up for floor-standing equipment/system 94

Figure H.5 – Example of test set-up in GTEM waveguide 95

Figure I.1 – Example of the measurement points for the validation 102

Figure I.2 – Set-up for calibration of E-field probe in one-port TEM waveguide 103

Figure I.3 – Cone and ground plane sensor calibration set-up 104

Table 1 – Possible IEMI deployment scenarios 17

Table 2 – Summary of high power radiated IEMI source output (rE_{far}) by capability group 18

Table 3 – Examples of protection levels 19

Table 4 – Generic hyperband test parameters (skilled capability group) 24

Table 5 – Radiated hyperband test waveform and other pulse parameters 24

Table 6 – Generic mesoband test parameters (skilled capability group) 25

Table 7 – Comparison of quality factor (Q) with bandratio 26

Table 8 – Radiated mesoband waveform and other pulse parameters 26

Table 9 – Generic hypoband/narrowband test parameters (skilled capability group) 27

Table 10 – Conducted IEMI test levels 28

Table 11 – Open circuit specifications 29

Table 12 – Short circuit specifications 30

Table A.1 – Recommended performance criteria 35

Table B.1 – IEMI environments from IEC 61000-2-13 43

Table B.2 – Hypoband/narrowband HPM environment from [B.17] 44

Table B.3 – Wideband (mesoband/hyperband) HPM environment from [B.17] 44

Table C.1 – Shielding effectiveness measurements for various power system buildings and rooms 51

Table E.1 – Time waveform norms 70

Table I.1 – Calibration frequencies 102

Table I.2 – Type B expanded uncertainties for sensor calibrations in GTEM cell field generation system 105

Table I.3 – Type B expanded uncertainties for sensor calibrations in the cone and ground plane cell field generation system 106

INTERNATIONAL ELECTROTECHNICAL COMMISSION

ELECTROMAGNETIC COMPATIBILITY (EMC) –**Part 4-36: Testing and measurement techniques –
IEMI immunity test methods for equipment and systems**

FOREWORD

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International Standard IEC 61000-4-36 has been prepared by subcommittee 77C: High power transient phenomena, of IEC technical committee 77: Electromagnetic compatibility.

It forms part 4-36 of IEC 61000. It has the status of a basic EMC publication in accordance with IEC Guide 107.

This second edition cancels and replaces the first edition published in 2014. This edition constitutes a technical revision.

This edition includes the following significant technical changes with respect to the previous edition:

- a) addition of a hyperband and mesoband radiated transients immunity test method in Annex H;
- b) addition of a calibration method of sensors for radiated hyperband and mesoband transient fields and measurement uncertainty in Annex I.

The text of this International Standard is based on the following documents:

| FDIS | Report on voting |
|--------------|------------------|
| 77C/295/FDIS | 77C/299/RVD |

Full information on the voting for the approval of this standard can be found in the report on voting indicated in the above table.

This publication has been drafted in accordance with the ISO/IEC Directives, Part 2.

A list of all parts in the IEC 61000 series, published under the general title *Electromagnetic compatibility (EMC)*, can be found on the IEC website.

The committee has decided that the contents of this publication will remain unchanged until the stability date indicated on the IEC website under "<http://webstore.iec.ch>" in the data related to the specific publication. At this date, the publication will be

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INTRODUCTION

IEC 61000 is published in separate parts according to the following structure:

Part 1: General

General considerations (introduction, fundamental principles)

Definitions, terminology

Part 2: Environment

Description of the environment

Classification of the environment

Compatibility levels

Part 3: Limits

Emission limits

Immunity limits (in so far as they do not fall under the responsibility of the product committees)

Part 4: Testing and measurement techniques

Measurement techniques

Testing techniques

Part 5: Installation and mitigation guidelines

Installation guidelines

Mitigation methods and devices

Part 6: Generic standards

Part 9: Miscellaneous

Each part is further subdivided into several parts, published either as international standards or as technical specifications or technical reports, some of which have already been published as sections. Others will be published with the part number followed by a dash and a second number identifying the subdivision (example: IEC 61000-6-1).